

AIOT-X1000

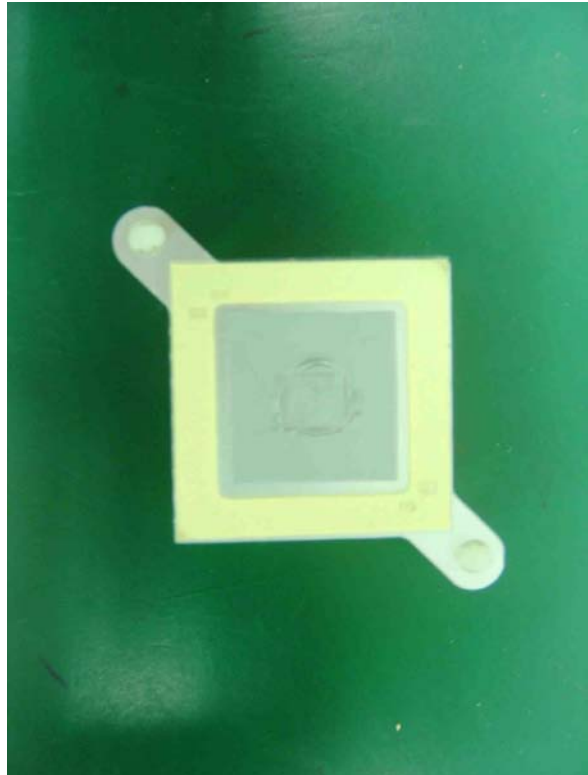
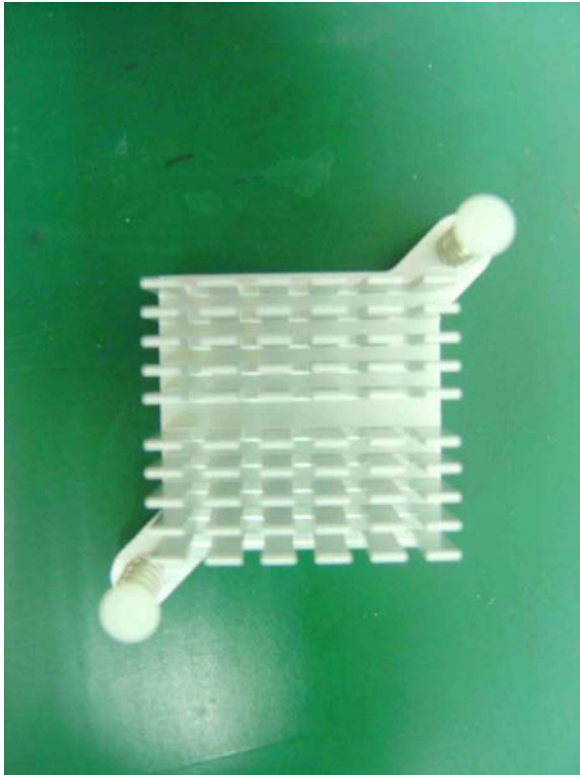
Thermal Image Analysis Report

| | | | | |
|-----------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------|-------|-------|-------------|
| Summary | <input checked="" type="checkbox"/> Pass <input type="checkbox"/> Fail <input type="checkbox"/> Pass with Deviation Comment: | | | |
| | Test Result Summary | | | |
| | Critical | Major | Minor | Enhancement |
| Defect Found | 0 | 0 | 0 | 0 |
| Defect Unsolved | 0 | 0 | 0 | 0 |

| | | |
|----------------|--------------|---------------|
| Issue date | Approval | Test Engineer |
| 2014 / 12 / 08 | Vincent Chen | Juno Cheng |

Sample Configuration & Quantity Under Test

- **Model name : AIOT-X1000 B0.3**
- **CPU Board : AIOT X1000 Rev. B0.3**
- **CPU : Intel Quark SoC X1020 400MHz**
- **Memory : On Board 1GB / DDR3 1600 / SAMSUNG.K4B4G0846D-BYK0**
- **SD Card : MICROSDHC10 Card.4G.MLC.Transcend.TS4GUSDC10**
- **BIOS : Wind River Linux 5.0.1.19**
- **Test Software : AAEON ON&OFF Test and AAEON Burnintest.**
- **Power : FSP.FSP060-DBAE1 / 12V / 5A / 60W**
- **Heat Sink :**



Thermal Image Analysis

1. Test Date: 2014-12-08

2. Test Product: AIOT-X1000

3. Test Site: AAEON QE Dept.

4. Temperature Measurement:

4.1. 40 Channel Thermal Recorder:

4.1.1 YOKOGAWA Inc,

4.2.2 Model: DA100-13-1D

Date of Calibration: 2014/09/11

Serial Number: 12A323190

4.2. IR Scanner: Infrared Camera

4.2.1 NEC Avio Infrared Technologies Co., Ltd.

4.2.2 Model: Thermo GEAR G100W2-D

Date of Calibration: 2013/12/30

Serial Number: 1051444

5. Test Condition:

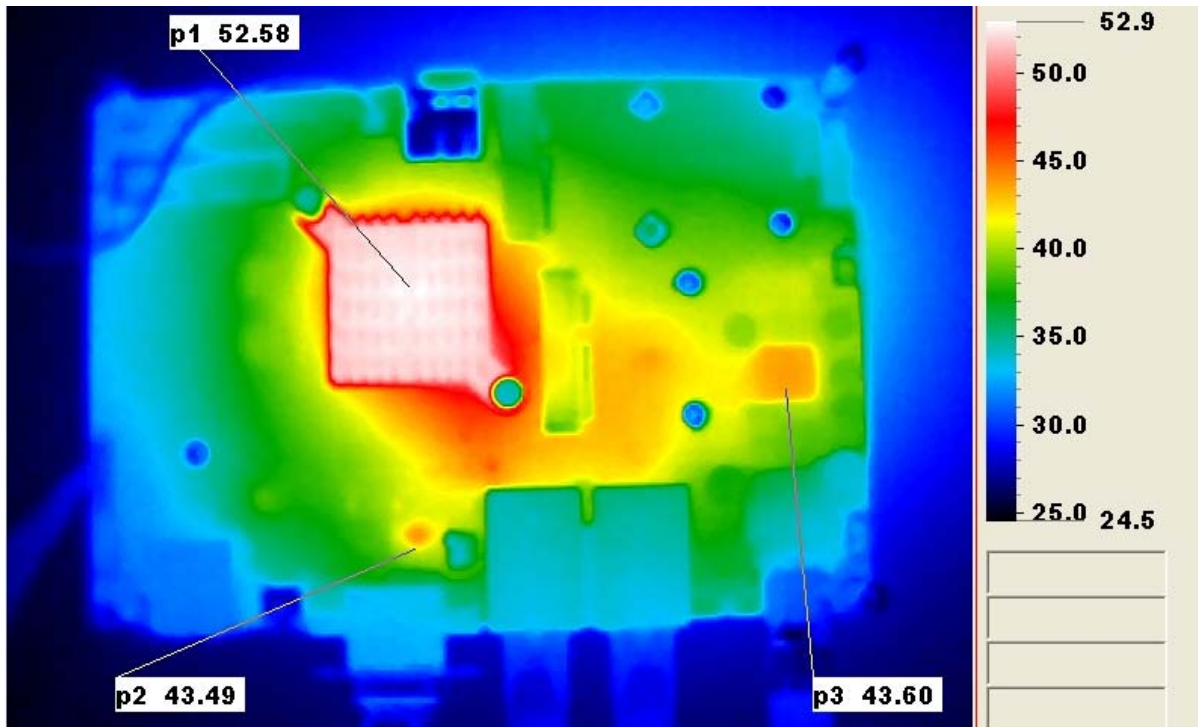
Test by DA-100: 25.0°C with Heat Sink + FAN (Full speed)

6. Take Picture Time:

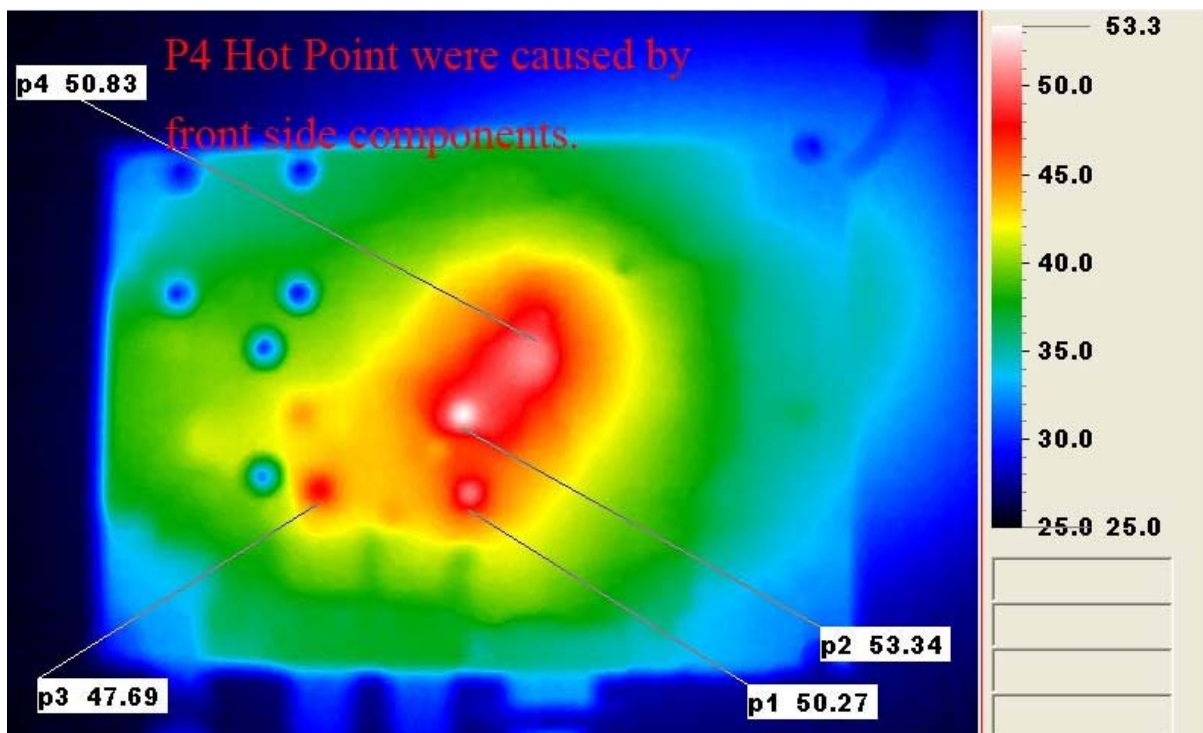
After power on 2 hours

Temperature Profile Test:

Component Side:

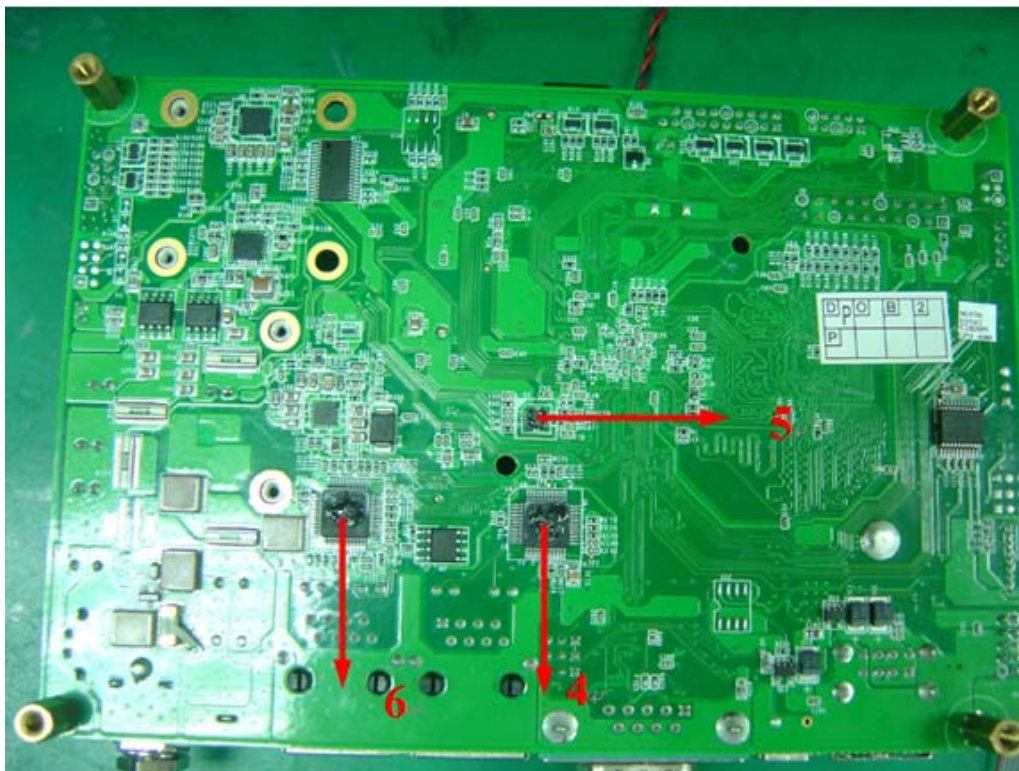
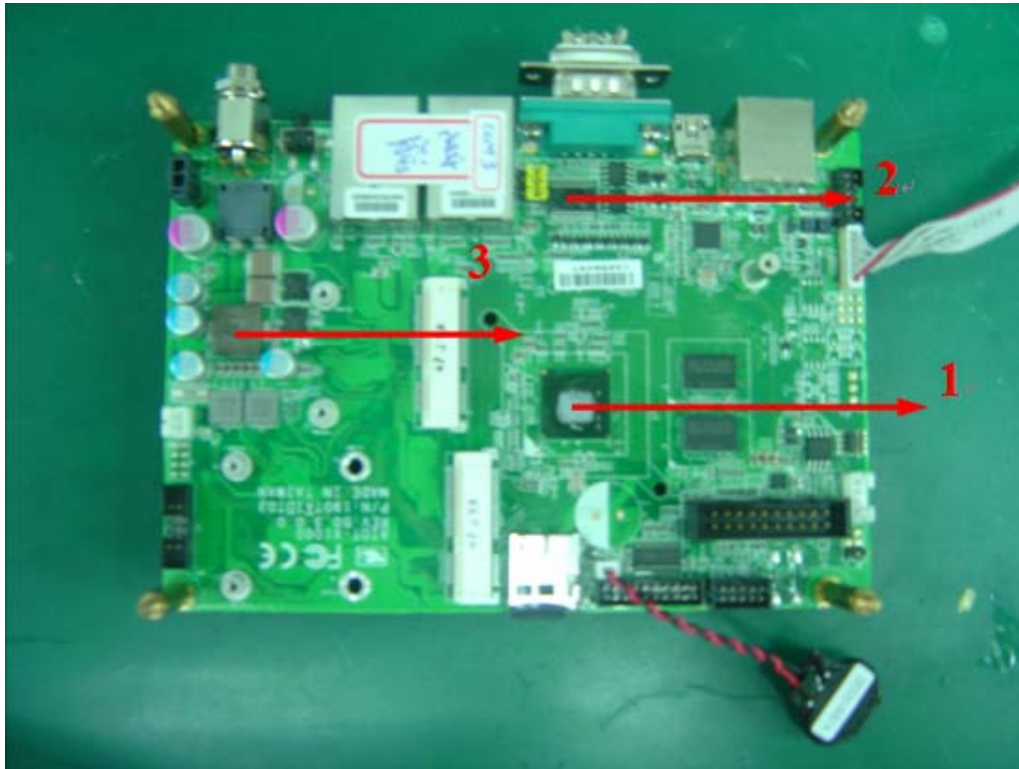


Back Side



Terminal Recorder :

Measuring Thermal Couple Position :



Using YOKOGAWA / DARWIN DA100-100-13-1D test

| Point | Position | Describe | Tc (*1) (°C) | Tm (*2) Measured Under | | Note |
|-------|----------|----------------------------------------------------|-----------------|---------------------------|------|------|
| | | | | 25.0°C | 60°C | |
| 1 | U1 | CPU.QUARK.PN#X1020D.400MHz.FCBGA | 110 | 54.3 | 89.3 | |
| 2 | U19 | (TF) IC.SMD Transceivers ESD .ADM3311EARSZ | 100 | 45.8 | 80.8 | |
| 3 | L11 | (TF)COIL. SMD.GOTREND.GSTD1040PE-6R8M | 140 | 44.8 | 79.8 | |
| 4 | U9 | (TF) IC. Ethernet.PHY LQFP DP83848IVVX/NOPB | 100 | 52.6 | 87.6 | |
| 5 | U3 | (TF)IC.LDO REG.ADJ. TPS74801DRCR | 140 | 57.9 | 72.9 | |
| 6 | U10 | (TF)IC. Ethernet.PHY Transceiver. DP83848IVVX/NOPB | 100 | 50.1 | 85.1 | |
| 7 | | (TF)BATTERY.3V.MAXELL.CR2032M1S8-LF | 85 | 28.8 | 63.8 | |

Note(*):

- "Tc" indicates the component's case maximum temperature value specified in its datasheet.
- "Tm" indicates the measured Tc value under working environmental temperature within product specification.
- Judgment Criteria:**
 - **Fail** : $T_m > T_c + 5^\circ\text{C}$; The measured value is over specification plus margin.
 - **Margin** : $T_c + 5^\circ\text{C} > T_m > T_c - 10^\circ\text{C}$; The measured value is within specification with margin.
For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
 - **Pass** : $T_m < T_c - 10^\circ\text{C}$; The measured value is with safety margin.
- Defect NO** : NA